SCLS517A - AUGUST 2003 - REVISED APRIL 2008

 Qualified for Automotive Applications ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0) 	D PACKAGE (TOP VIEW) 1A 1 14 V _{CC} 1B 2 13 4B
• 4.5-V to 5.5-V V _{CC} Operation	
 Inputs Accept Voltages to 5.5 V 	2A [] 4 11 [] 4Y
 Max t_{pd} of 8 ns at 5 V 	2B 🛛 5 10 🗋 3B
Inputs Are TTL-Voltage Compatible	2Y [6 9] 3A GND [7 8] 3Y

description/ordering information

The SN74ACT00 contains four independent 2-input NAND gates. Each gate performs the Boolean function of $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

TA	PAC	KAGE [‡]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	SOIC – D	Tape and reel	SN74ACT00TDRQ1	ACT00TQ1

⁺ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

[‡]Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

FUNCTION TABLE (each gate)										
INPUTS OUTPUT										
Α	В	Y								
Н	Н	L								
L	Х	н								
Х	L	н								



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logic diagram, each gate (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	$\dots \dots -0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{CC})	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±200 mA
Package thermal impedance, θ_{JA} (see Note 2)	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
IОН	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
ТА	Operating free-air temperature	-40	105	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS		Vaa	T	A = 25°C	;	MIN	МАХ	UNIT
PARAMETER	TEST CONDITIONS		VCC	MIN	TYP	MAX	IVITIN	WAX	UNIT
			4.5 V	4.4	4.49		4.4		
Maria	I _{OH} = -50 μA		5.5 V	5.4	5.49		5.4		N/
VOH			4.5 V	3.86			3.7		V
	I _{OH} = -24 mA		5.5 V	4.86			4.7		
	1 500		4.5 V		0.001	0.1		0.1	
	I _{OL} = 50 μA		5.5 V		0.001	0.1		0.1	V
V _{OL}			4.5 V			0.36		0.5	V
	I _{OL} = 24 mA		5.5 V			0.36		0.5	
li	$V_I = V_{CC}$ or GND		5.5 V			±0.1		±1	μΑ
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V			2		40	μΑ
ΔI_{CC}^{\dagger}	One input at 3.4 V, Other inputs at GND or V _{CC}		5.5 V		0.6			1.6	mA
Ci	$V_I = V_{CC}$ or GND		5 V		2.6				pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

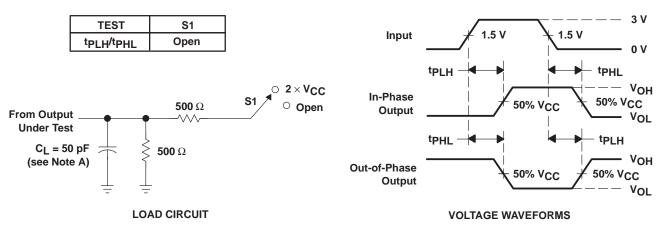
DADAMETED	FROM	то	Т	α = 25°C	;			
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
^t PLH	A or B	V	1.5	5.5	9	1	9.5	
^t PHL		ſ	1.5	4	7	1	8	ns

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	TYP	UNIT	
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	40	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT00TDRQ1	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	ACT00TQ1	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74ACT00-Q1 :



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PACKAGE OPTION ADDENDUM

10-Dec-2020

• Catalog: SN74ACT00

Military: SN54ACT00

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



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